

HD74HC75

Quad. Bistable Latches

REJ03D0550-0200
(Previous ADE-205-422)
Rev.2.00
Oct 06, 2005

Description

This latch is ideally suited for use as temporary storage for binary information processing, input/output, and indicator units. Information present at the data (D) input is transferred to the Q output when the latch enable (LE) is high. The Q output will follow the data input as long as the enable remains high. When the enable goes low, the information that was present at the data input at the time the transition occurred is retained at the Q output unit the enable is permitted to go high again.

Features

- High Speed Operation: t_{pd} (D to Q) = 12.5 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 2 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC75P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74HC75FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74HC75RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Function Table

Inputs		Outputs	
Data	Latch Enable	Q	$\bar{Q}$
L	H	L	H
H	H	H	L
X	L	Q_0	$\bar{Q}_0$

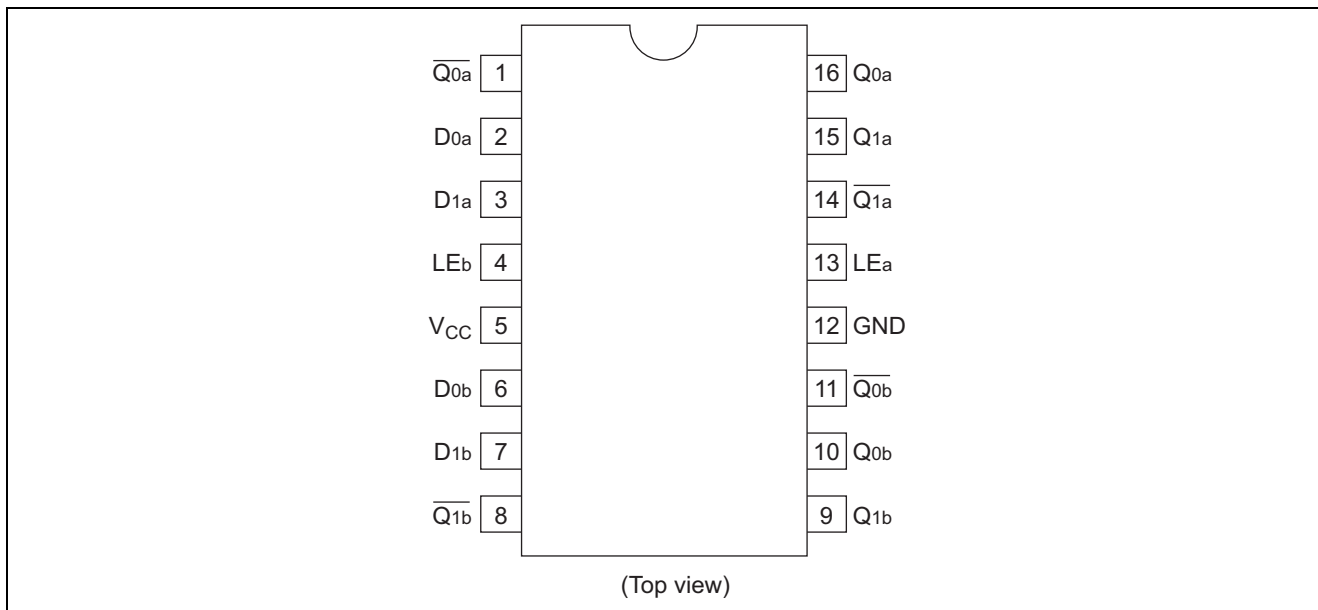
H : High level

L : Low level

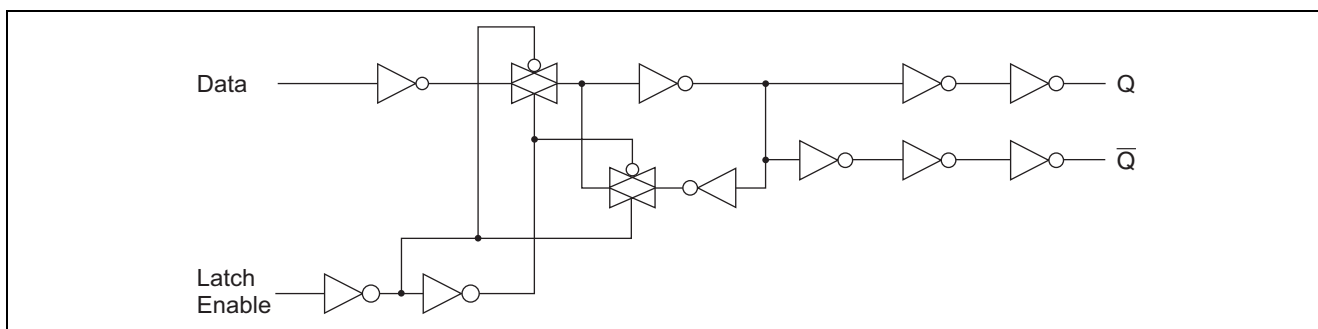
X : Irrelevant

$Q_0, \bar{Q}_0$: Output level before the indicated steady state input conditions were established.

Pin Arrangement



Logic Diagram (1/4)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{in}, V_{out}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_O	± 25	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2 to 6	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	°C	
Input rise / fall time ^{*1}	t_r, t_f	0 to 1000	ns	$V_{CC} = 2.0\text{ V}$
		0 to 500		$V_{CC} = 4.5\text{ V}$
		0 to 400		$V_{CC} = 6.0\text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

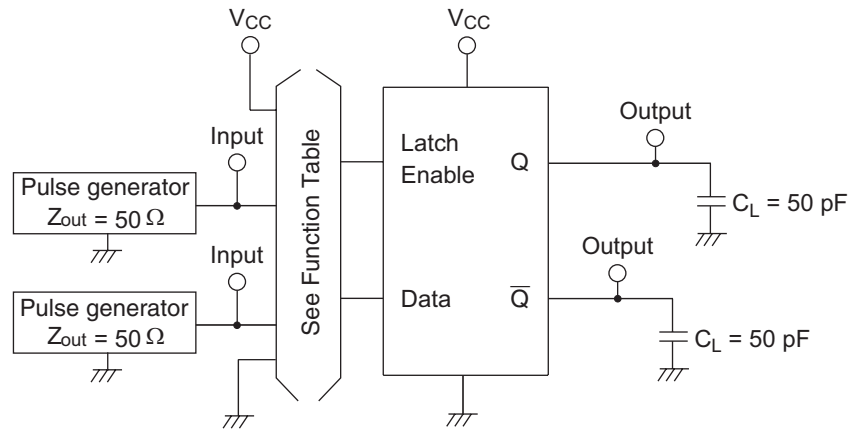
Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40\text{ to }+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V_{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	$V_{in} = V_{IH}\text{ or }V_{IL}$	$I_{OH} = -20\text{ }\mu\text{A}$
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			$I_{OH} = -4\text{ mA}$
		6.0	5.68	—	—	5.63	—			$I_{OH} = -5.2\text{ mA}$
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	$V_{in} = V_{IH}\text{ or }V_{IL}$	$I_{OL} = 20\text{ }\mu\text{A}$
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			$I_{OL} = 4\text{ mA}$
		6.0	—	—	0.26	—	0.33			$I_{OL} = 5.2\text{ mA}$
Input current	I_{in}	6.0	—	—	± 0.1	—	± 1.0	μA	$V_{in} = V_{CC}\text{ or GND}$	
Quiescent supply current	I_{CC}	6.0	—	—	2.0	—	20	μA	$V_{in} = V_{CC}\text{ or GND}, I_{out} = 0\text{ }\mu\text{A}$	

Switching Characteristics ($C_L = 50\text{ pF}$, Input $t_r = t_f = 6\text{ ns}$)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40\text{ to }+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Propagation delay time	t_{PLH}, t_{PHL}	2.0	—	—	125	—	155	ns	Data to Q	
		4.5	—	12	25	—	31			
		6.0	—	—	21	—	26			
		2.0	—	—	110	—	140	ns	Data to $\bar{Q}$	
		4.5	—	13	22	—	28			
		6.0	—	—	19	—	24			
		2.0	—	—	145	—	180	ns	Latch Enable to Q	
		4.5	—	12	29	—	36			
		6.0	—	—	25	—	31			
		2.0	—	—	125	—	155	ns	Latch Enable to $\bar{Q}$	
		4.5	—	13	25	—	31			
		6.0	—	—	21	—	26			

Switching Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

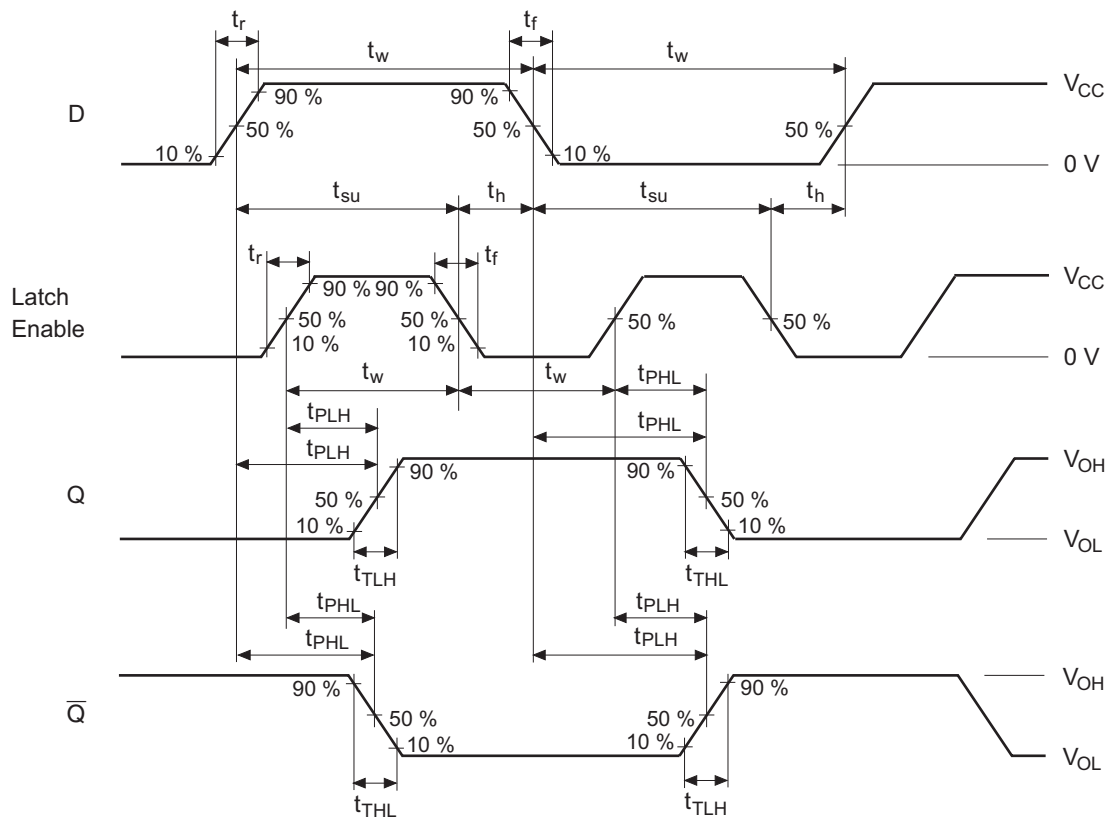
Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } +85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Setup time	t_{su}	2.0	100	—	—	125	—	ns	Data to Latch Enable
		4.5	20	4	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	Latch Enable to Data
		4.5	5	0	—	5	—		
		6.0	5	—	—	5	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	Latch Enable
		4.5	16	5	—	20	—		
		6.0	14	—	—	17	—		
Output rise/fall time	t_{TLH}, t_{THL}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

Test Circuit

Note: C_L includes the probe and jig capacitance.

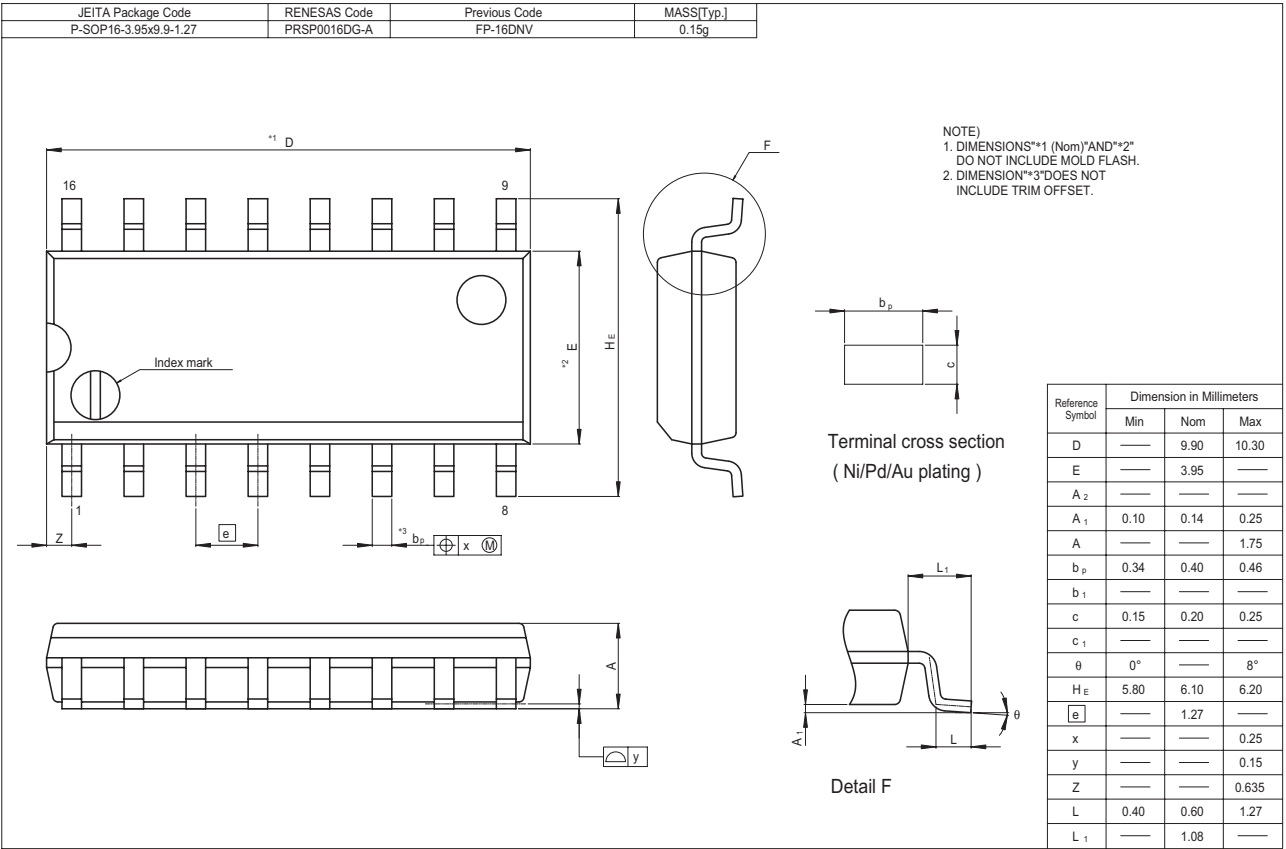
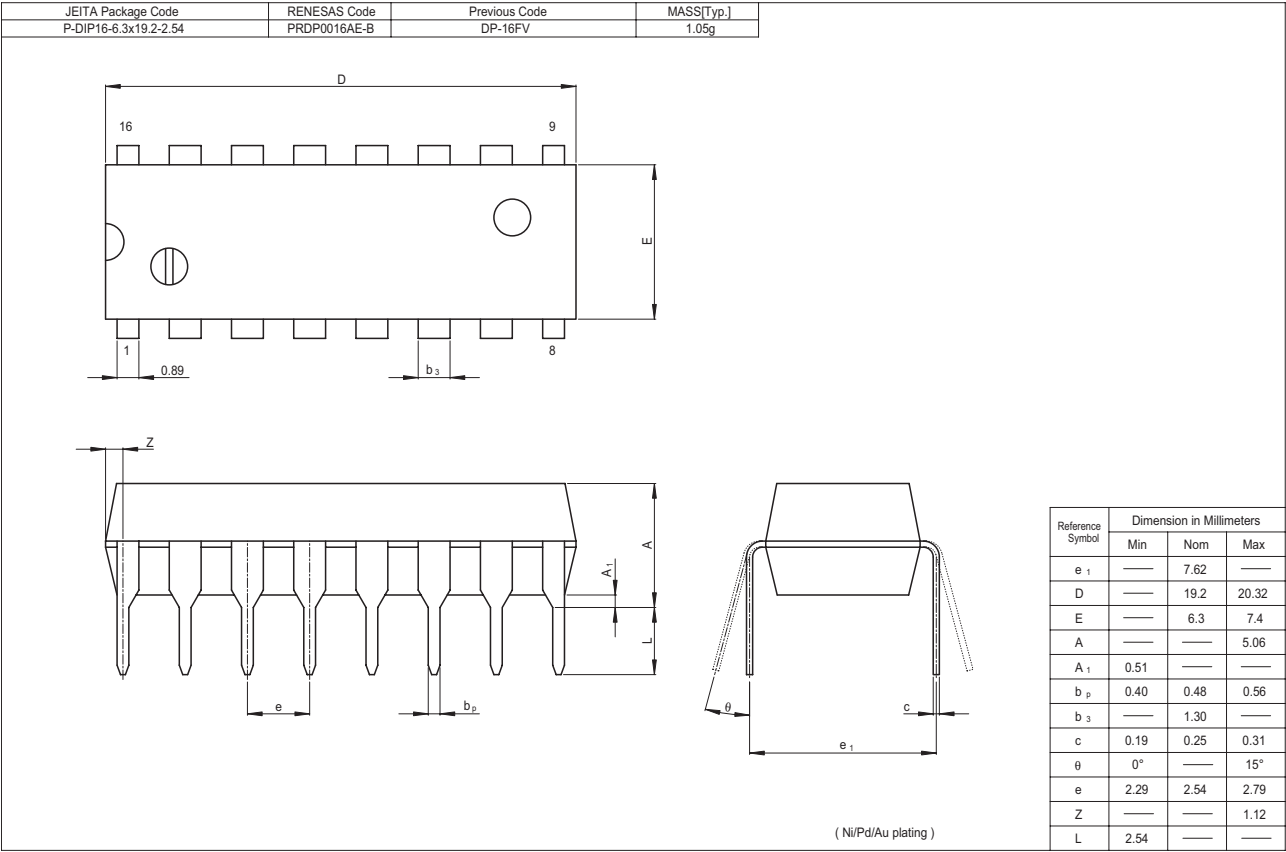
Waveforms

• Waveform – 1

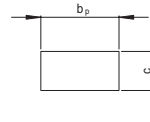
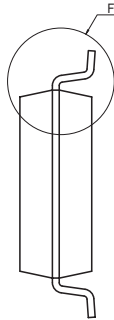
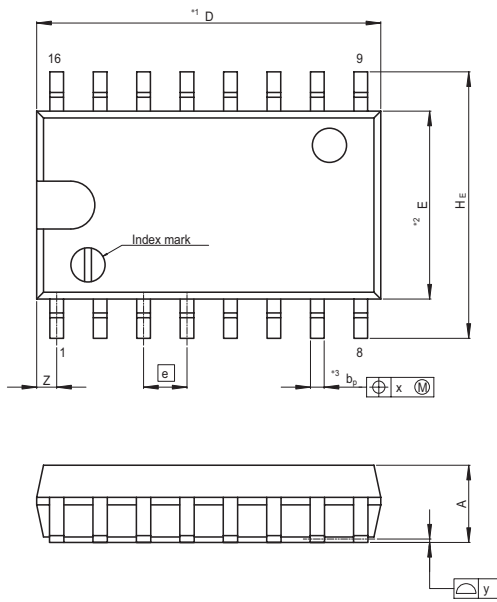


Note: 1. Input waveform: $PRR \leq 1 \text{ MHz}$, $Z_o = 50 \Omega$, $t_r \leq 6 \text{ ns}$, $t_f \leq 6 \text{ ns}$

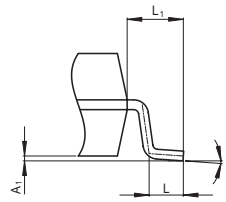
Package Dimensions



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-5.5x10.06-1.27	PRSP0016DH-B	FP-16DAV	0.24g



Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS*1 (Nom)*AND*2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION*3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

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